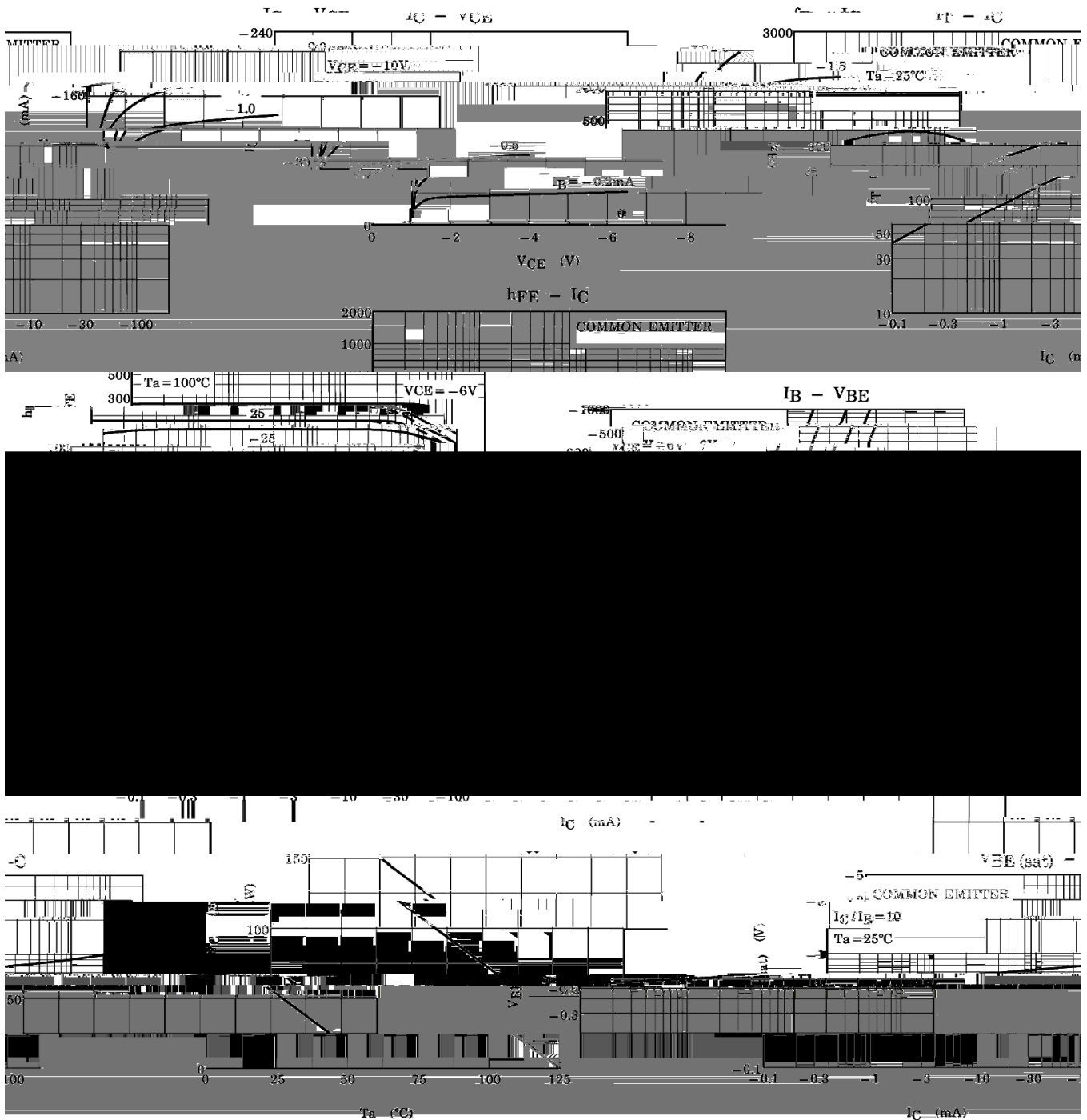
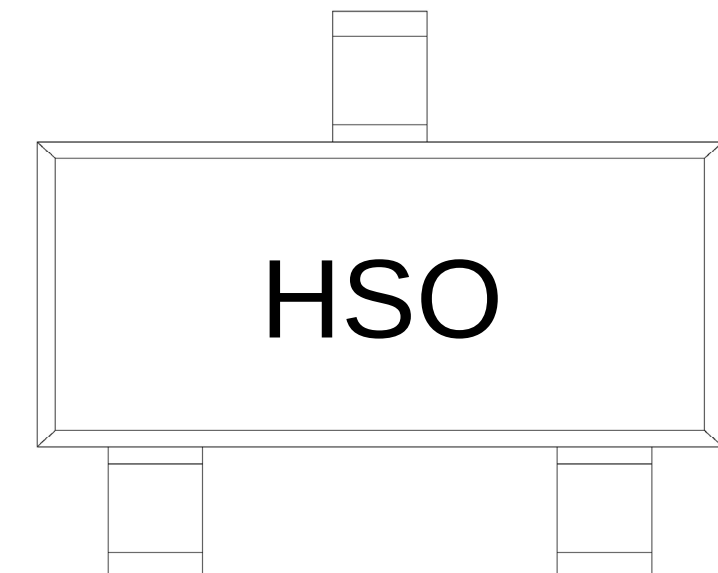


Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-50	V
Collector to Emitter Voltage	V_{CEO}	-50	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current	I_C	-150	mA
Base Current	I_B	-30	mA
Collector Power Dissipation	P_C	150	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 ~ 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector Cut-Off Current	I_{CBO}	$V_{CB}=-50V$ $I_E=0$			-0.1	μA
Emitter Base Cut-Off Current	I_{EBO}	$V_{EB}=-5.0V$ $I_C=0$			-0.1	μA
DC Current Gain	h_{FE}	$V_{CE}=-6.0V$ $I_C=-2.0mA$	70		400	
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=-100mA$ $I_B=-2.0mA$		-0.1	-0.3	V
Transition Frequency	f_T	$V_{CE}=-10V$ $I_E=-1.0mA$	80			MHz



-



符号

K 芯片

V 芯片

R= 芯片

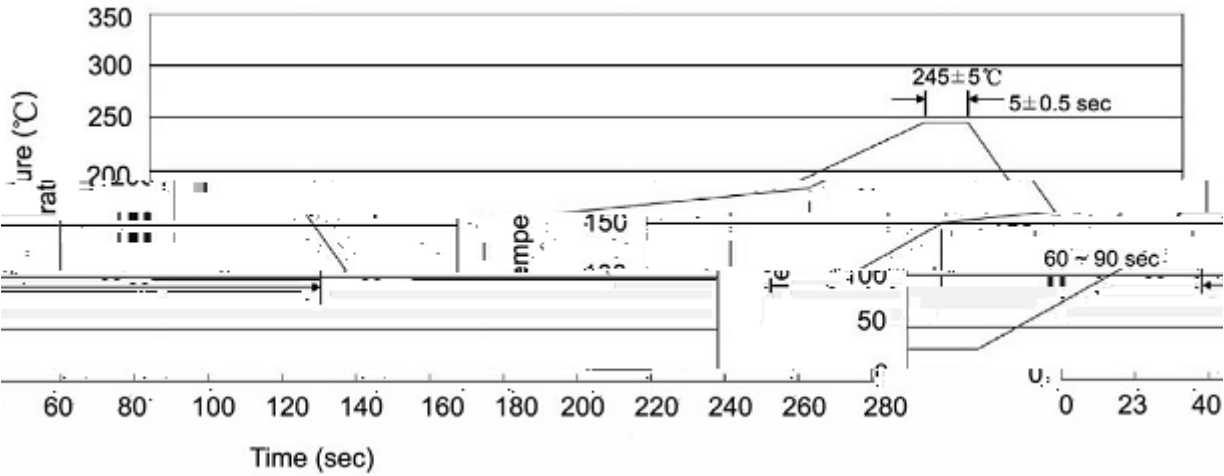
Note:

H: Company Code.

S: Product Type Code

O: h_{FE} Classifications Symbol Code

Temperature Profile for IR Reflow Soldering(Pb-Free)



注意

- 1. 预热: 25~150 °C, 时间: 60~90sec;
- 2. 峰值温度: 245±5 °C, 持续时间: 5±0.5sec;
- 3. 冷却速度: 2~10 °C/sec.

Note:

- 1.Preheating:25~150 °C, Time:60~90sec.
- 2.Peak Temp.:245±5 °C, Duration:5±0.5sec.
- 3. Cooling Speed: 2~10 °C/sec.

锡膏温度: 260±5 °C 时间: 10±1 sec. Temp.:260±5 Time:10±1 sec

包装形式 / REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
SOT-23	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205